

ABSTRACT OF THE DISCLOSURE

A method and an apparatus for precisely exposing a predetermined width of a peripheral area of a wafer coated with a layer of photoresist material with light from a light source, wherein the wafer is moved when the light is radiated onto the wafer to expose the photoresist layer at the peripheral area of the wafer, an inspection section inspecting whether the light is radiated onto a precise position of the peripheral area of the wafer, whereby by adjusting the position of the light source if the light is not radiated at the precise position of the peripheral area of the wafer requiring exposure while inspecting the light radiated onto the peripheral area of the wafer, the predetermined width of the peripheral area of the wafer is precisely exposed.